MBE system

RC1100



MBE system (RC1100) supplied to Hokkaido Universit

Features

RC1100 Series is a low-cost, space-saving and high performance MBE system for research purpose. For all its compact-size, it is adequate for full-fledged research. The combined use with an analyzer like STM system provides a way for the development of new materials.

Specifications

• Substrate size : $1 \times \phi$ 1" • K-Cell ports : $6 \times ICF114$

RC2100/RC3100



RC2100/RC3100 Series is an MBE system optimum for higher level of research and semi-production. This system supports the use of a variety of materials such as Nitride, ZnO.

Specifications

• Substrate size : 1 \times ϕ 2" (RC2100)

 $1 \times \phi 3$ " (RC3100)

● K-Cell ports : 8 × ICF114 (RC2100)

8 × ICF152 (RC3100)

RC6100



Features

The K-Cell-substrate arrangement designed by the most advanced molecular beam simulation technology achieves extremely uniform crystal growth on a large-area substrate.

Specifications

• Substrate size : $1 \times \phi 6$ "

• K-Cell ports : $10 \times ICF152$

MBE system (RC6100) supplied to National Institute of Advanced Industrial Science and Technology

■MBE System Specifications

Model		RC1100	RC2100/RC3100	RC6100	
Growth Chamber	Ultimate Pressure (Pa)		<1.33×10 ⁻⁸	<1.33×10 ⁻⁸	<1.33×10 ⁻⁸
	Substrate (wafer) size		1 × φ1"	$1 \times \phi 2$ " $/ 1 \times \phi 3$ "	1× φ6"
	Substrate temperature (T. C. Value for control)	Standard	900℃	900°C	900°C
		Optional	1200℃	1200°C	1200°C
	K-Cell ports		6 × ICF114	8 X ICF114 / 8 × ICF152	10 × ICF152
	Beam flux monitor		Standard	Standard	Standard
	Ion Pump		270I/sec	500I/sec	500I/sec
	Turbo Molecular Pump		Optional	Optional	Optional
	Cryo Pump		Not Available	Optional	Optional
	RHEED (30keV)		Standard	Standard	Standard
	RHEED screen size		ICF152	ICF152/ICF203	ICF203
Transfer Chamber (with Transfer Rod)	Ultimate Pressure (Pa)		<1.33×10 ⁻⁷	<1.33×10 ⁻⁷	<1.33×10 ⁻⁷
	Combination Pump		150I/sec	150I/sec	150l/sec
	Transfer system		Transfer Rod	Transfer Rod	Transfer Rod
	Rail transfer system		Optional	Optional	Optional
Transfer Chamber (with arm transfer system)	Ultimate Pressure (Pa)		<1.33×10 ⁻⁷	<1.33×10 ⁻⁷	<1.33×10 ⁻⁷
	Combination Pump		300I/sec	300I/sec	300I/sec
	Transfer system		Arm transfer system	Arm transfer system	Arm transfer system
	Extension ports (amount × size)		2 × ICF152	2 × ICF152	2 × ICF203
Load lock Chamber	Ultimate Pressure (Pa)		<1.33×10 ⁻⁵	<1.33×10 ⁻⁵	<1.33×10 ⁻⁵
	Turbo Molecular Pump		300I/sec	300I/sec	300l/sec
	Pre-heating system (Max500°C)		Standard	Standard	Standard
	Substrate stock stage (for up to 4 holders)		Standard	Standard	Standard
	Transfer system Unnecessary in case of arm transfer system		Transfer Rod or Rail transfer system	Transfer Rod or Rail transfer system	Transfer Rod or Rail transfer system
Control system	Operation panel		Standard	Standard	Standard
	Alarm system		Standard	Standard	Standard
	Inter lock system		Standard	Standard	Standard
	Automatic Growth system (for shutter)		Optional	Optional	Optional
	Automatic Growth system (for temperature)		Optional	Optional	Optional
Others	Residual Gas Analyzer	S	Optional	Optional	Optional

High temperature vacuum baking system



Features

We are ready to offer design and manufacture of high-temperature vacuum baking system to meet various types of applications.

Specifications

■ Maximum heating: from 1000°C up to 2000°C temperature

 \blacksquare Ultimate pressure $: < 1.33 \times 10^{\text{-4}} Pa$ (using TMP)

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